

# PS2911-1

R08DS0110EJ0600

Rev.6.00

HIGH CTR, 4-PIN ULTRA SMALL FLAT-LEAD PHOTOCOUPLER

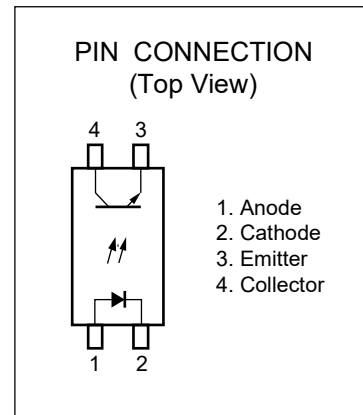
Feb. 2, 2026

## DESCRIPTION

The PS2911-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor in one package for high density mounting applications. An ultra small flat-lead package has been provided which realizes a reduction in mounting area of about 30 % compared with the PS28xx series.

## FEATURES

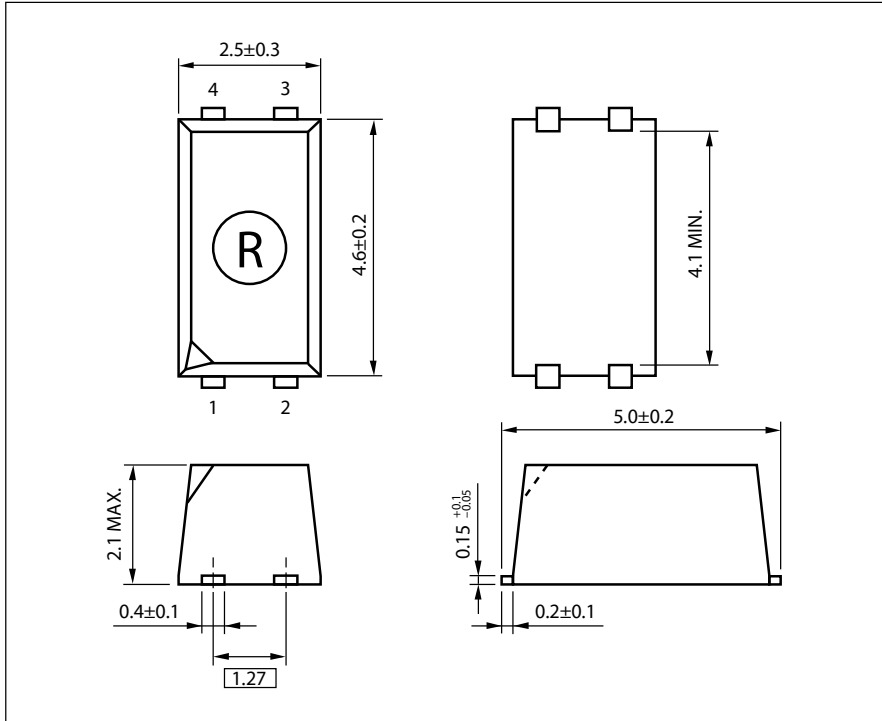
- Ultra small flat-lead package (4.6 (W) × 2.5 (L) × 2.1 (H) mm)
- High current transfer ratio (CTR = 200 % TYP. @  $I_F = 1 \text{ mA}$ ,  $V_{CE} = 5 \text{ V}$ )
- High isolation voltage (BV = 2 500 Vr.m.s.)
- Embossed tape product: PS2911-1-F3: 3 500 pcs/reel
- Pb-free product
- Safety standards
  - UL approved: UL 1577, Single protection
  - BSI approved: BS EN IEC 62368-1, Supplementary insulation
  - VDE approved: DIN EN IEC 60747-5-5 (Option)



## APPLICATIONS

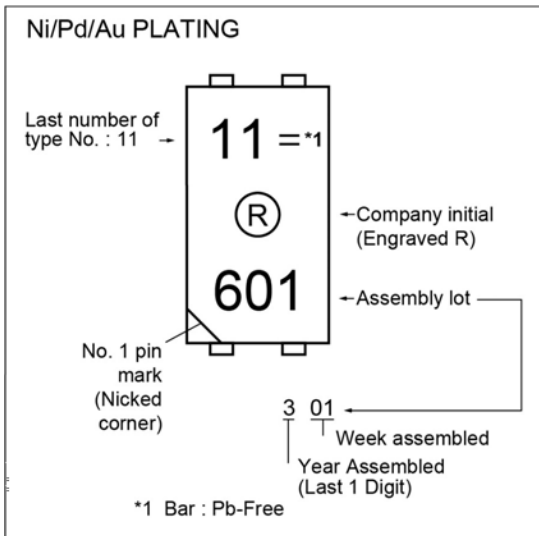
- DC / DC converter
- Modem / PC card

**PACKAGE DIMENSIONS (UNIT: mm)**



Weight: 0.05g (TYP.)

**MARKING EXAMPLE**



**PHOTOCOUPLER CONSTRUCTION**

Parameter	MIN.
Air Distance	4 mm
Creepage Distance	4 mm
Isolation Distance	0.4 mm

## ORDERING INFORMATION

Part Number	Order Number *1	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number *2
PS2911-1	PS2911-1-AX	Pb-Free (Ni/Pd/Au)	Embossed Tape 50 pcs	Standard Products (UL, BSI Approved)	PS2911-1
PS2911-1-F3	PS2911-1-F3-AX		Embossed Tape 3 500 pcs/reel		
PS2911-1-V	PS2911-1-V-AX		Embossed Tape 50 pcs	UL, BSI, VDE Approved	
PS2911-1-V-F3	PS2911-1-V-F3-AX		Embossed Tape 3 500 pcs/reel		

Note: \*1. When specifying CTR rank, please add "-CTR rank" after Order Number.  
ex. L rank : PS2911-1-AX-L

Note: \*2. For the application of the safety standard, the following part number should be used.

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	$I_F$	50	mA
	Peak Forward Current *1	$I_{FP}$	0.5	A
	Power Dissipation *2	$P_D$	60	mW
	Reverse Voltage	$V_R$	6	V
Detector	Collector to Emitter Voltage	$V_{CEO}$	40	V
	Emitter to Collector Voltage	$V_{ECO}$	5	V
	Collector Current	$I_C$	40	mA
	Power Dissipation *3	$P_C$	120	mW
Isolation Voltage *4		$BV$	2 500	Vr.m.s.
Total Power Dissipation		$P_T$	160	mW
Operating Ambient Temperature		$T_A$	-55 to +100	$^\circ\text{C}$
Storage Temperature		$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note: \*1. Reduced to 0.5 mA/ $^\circ\text{C}$  at  $T_A = 25\text{ }^\circ\text{C}$  or more.

\*2. PW = 100  $\mu\text{s}$ , Duty Cycle = 1 %

\*3. Reduced to 1.2 mW/ $^\circ\text{C}$  at  $T_A = 25\text{ }^\circ\text{C}$  or more.

\*4. AC voltage for 1 minute at  $T_A = 25\text{ }^\circ\text{C}$ , RH = 60 % between input and output.

Pins 1-2 shorted together, 3-4 shorted together

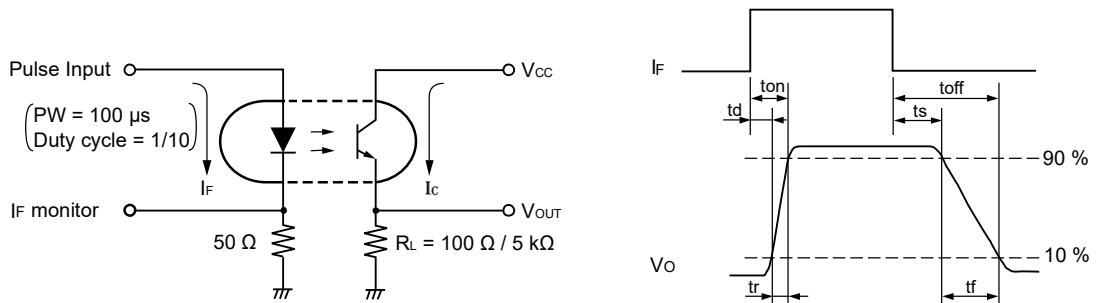
**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C)**

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 1 mA	0.9	1.1	1.3	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V			5	μA
	Terminal Capacitance	C <sub>t</sub>	V = 0 V, f = 1 MHz		15		pF
Transistor	Collector to Emitter Dark Current	I <sub>CEO</sub>	I <sub>F</sub> = 0 mA, V <sub>CE</sub> = 40 V			100	nA
Coupled	Current Transfer Ratio (I <sub>c</sub> /I <sub>F</sub> ) *1	CTR	I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 5 V	100	200	400	%
	Collector Saturation Voltage	V <sub>CE(SAT)</sub>	I <sub>F</sub> = 1 mA, I <sub>c</sub> = 0.2 mA		0.13	0.3	V
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1 kV <sub>DC</sub>	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time *2	t <sub>r</sub>	V <sub>CC</sub> = 5 V, I <sub>c</sub> = 2 mA, R <sub>L</sub> = 100 Ω		5		μs
	Fall Time *2	t <sub>f</sub>			10		
	Turn-on Time *2	t <sub>on</sub>	V <sub>CC</sub> = 5 V, I <sub>F</sub> = 1 mA, R <sub>L</sub> = 5 kΩ		40		μs
	Storage Time *2	t <sub>s</sub>			10		
Turn-off Time *2	t <sub>off</sub>			120			

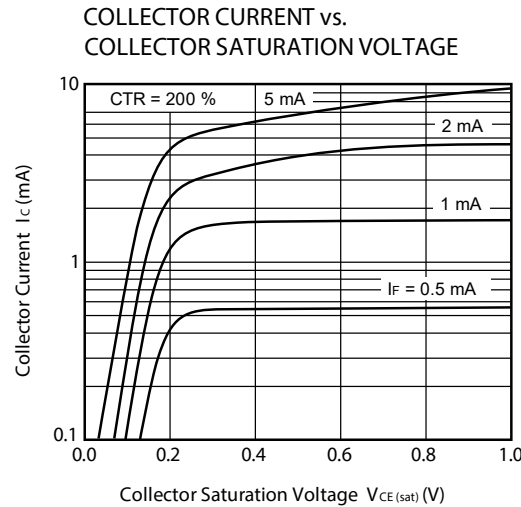
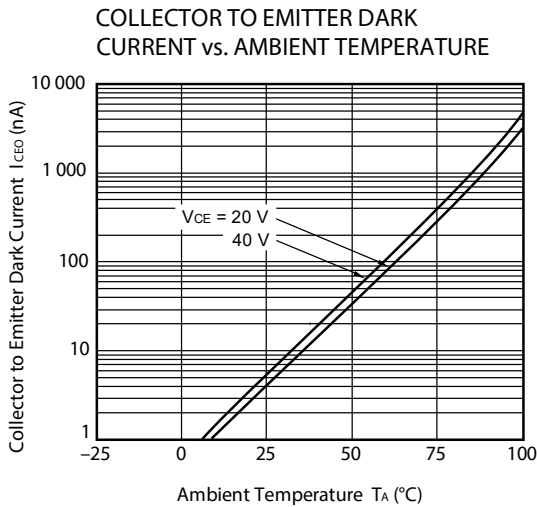
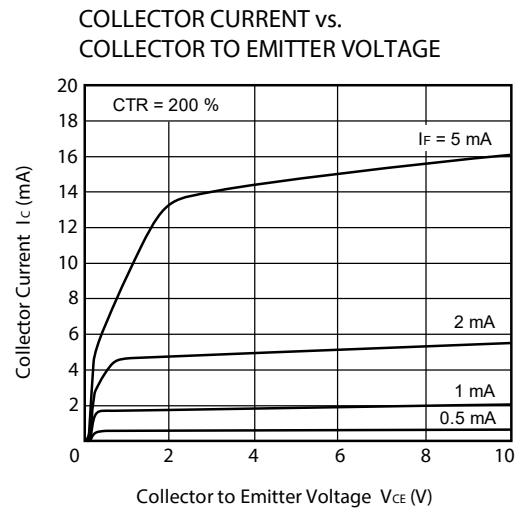
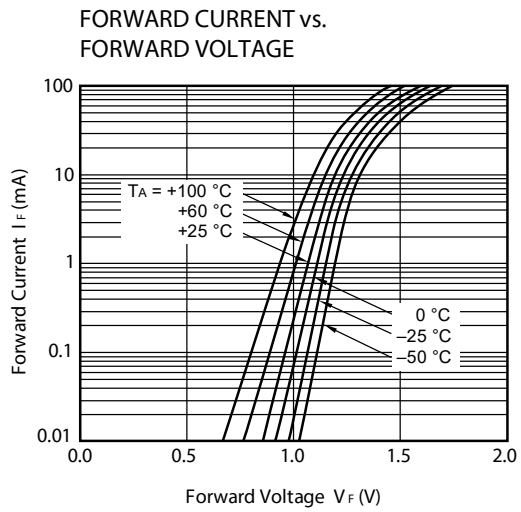
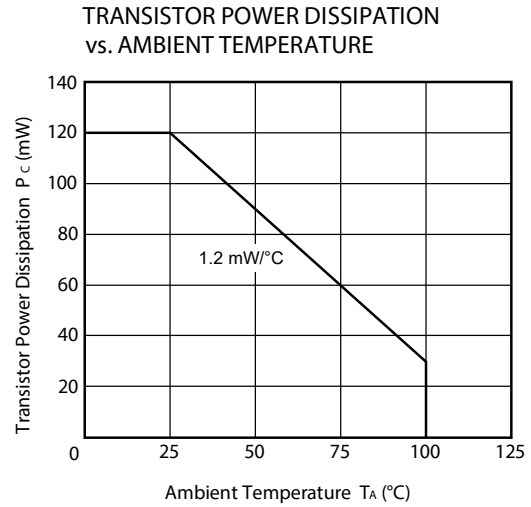
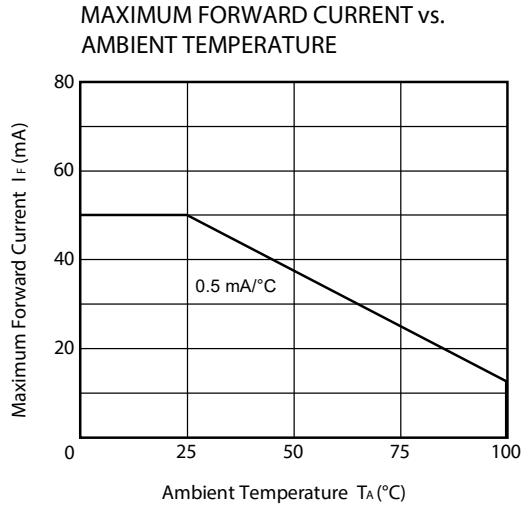
Notes: \*1. CTR rank

- N : 100 to 400 (%)
- K : 200 to 400 (%)
- L : 150 to 300 (%)
- M : 100 to 200 (%)

\*2. Test circuit for switching time

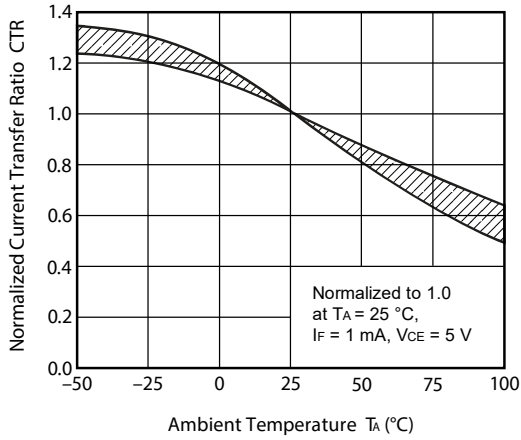


**TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise specified)**

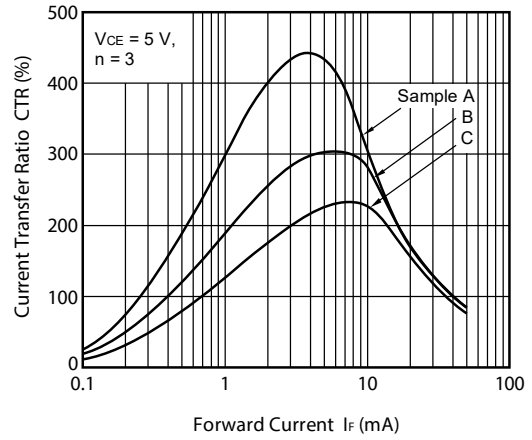


**Remark** The graphs indicate nominal characteristics.

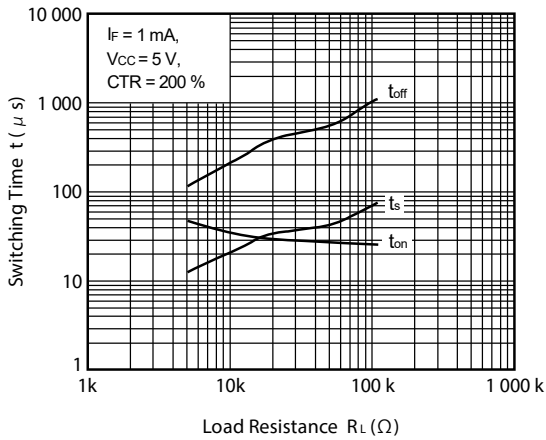
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



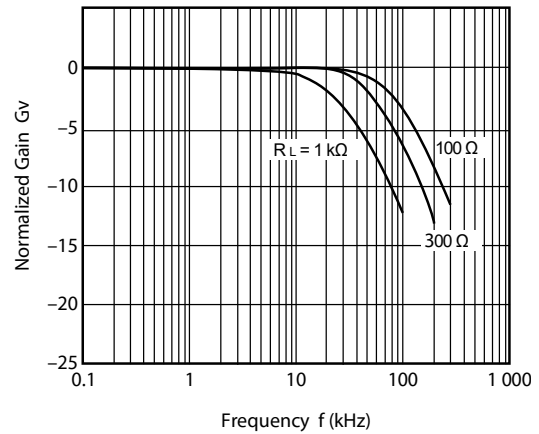
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



SWITCHING TIME vs. LOAD RESISTANCE



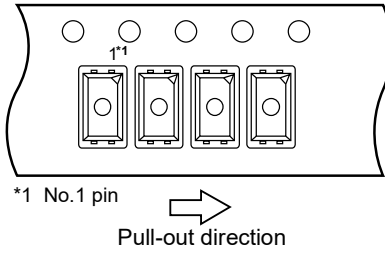
FREQUENCY RESPONSE



**Remark** The graphs indicate nominal characteristics.

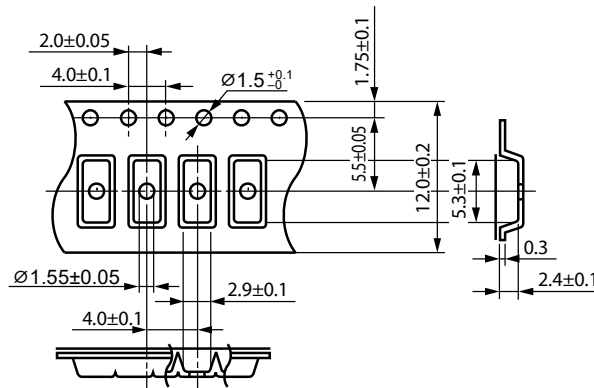
TAPING SPECIFICATIONS (UNIT: mm)

Tape Direction



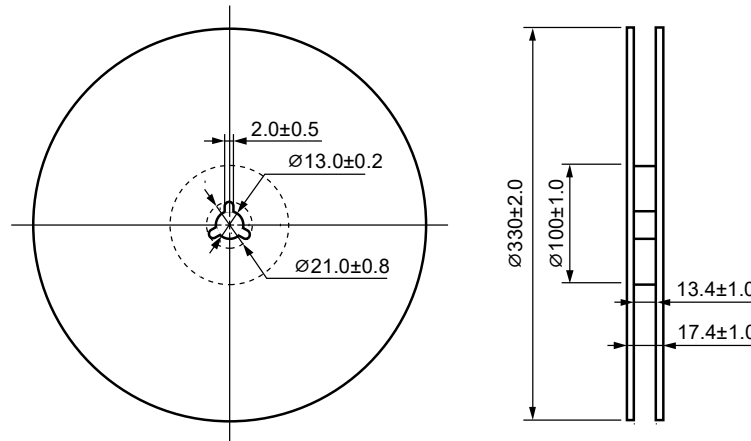
Outline and Dimensions (Tape)

(UNIT: mm)



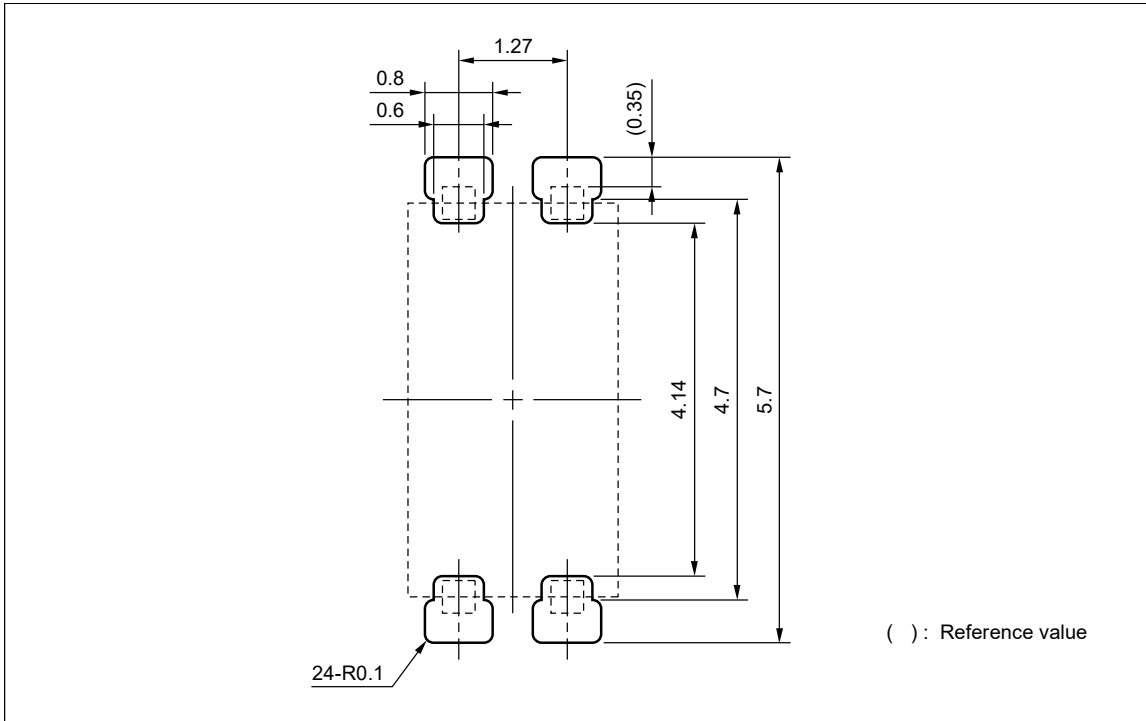
Outline and Dimensions (Reel)

(UNIT: mm)



Packing: 3 500 pcs/reel

## RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



**Remark** This drawing is considered to meet air and outer creepage distance 4.0 mm minimum. All dimensions in this figure must be evaluated before use.



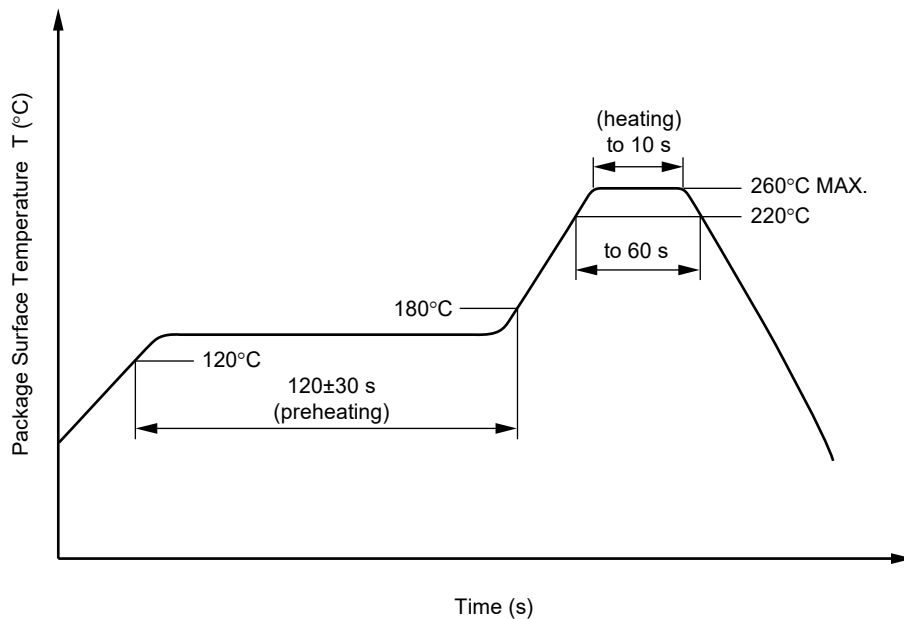
## NOTES ON HANDLING

### 1. Recommended soldering conditions

#### (1) Infrared reflow soldering

- |  |   |
|--|---|
| • Peak reflow temperature                        | 260 °C or below (package surface temperature)   |
| • Time of peak reflow temperature                | 10 s or less  |
| • Time of temperature higher than 220 °C         | 60 s or less  |
| • Time to preheat temperature from 120 to 180 °C | 120 ± 30 s  |
| • Number of reflows                              | Three   |
| • Flux   | Rosin flux containing small amount of chlorine<br>(The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Recommended Temperature Profile of Infrared Reflow



#### (2) Wave soldering

- |                         |  |
|-------------------------|--|
| • Temperature           | 260 °C or below (molten solder temperature)  |
| • Time                  | 10 s or less   |
| • Preheating conditions | 120 °C or below (package surface temperature)  |
| • Number of times       | One (Allowed to be dipped in solder including plastic mold portion.)   |
| • Flux                  | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

#### (3) Cautions

- |                  |  |
|------------------|--|
| • Flux cleaning  | Avoid cleaning with Freon- or halogen-based (chlorinated etc.) solvents. |
| • Fixing/Coating | Do not use fixing agents or coatings containing halogen-based substances |

### 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler  
Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.  
When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

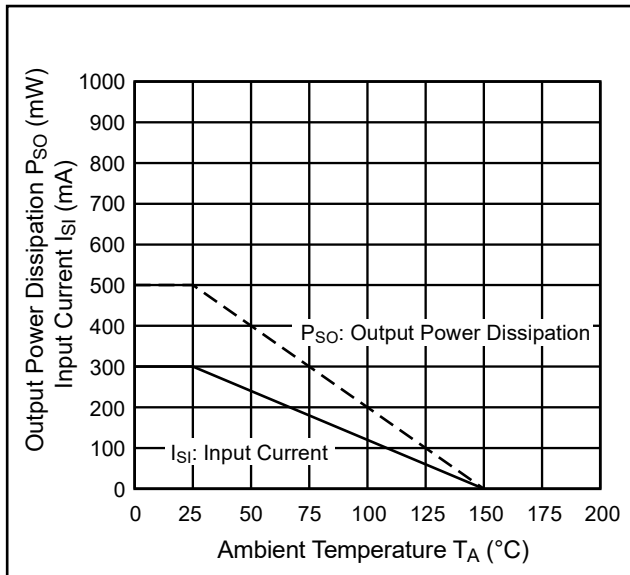
## USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.
3. Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
4. Do not use fixing agents or coatings containing halogen-based substances.

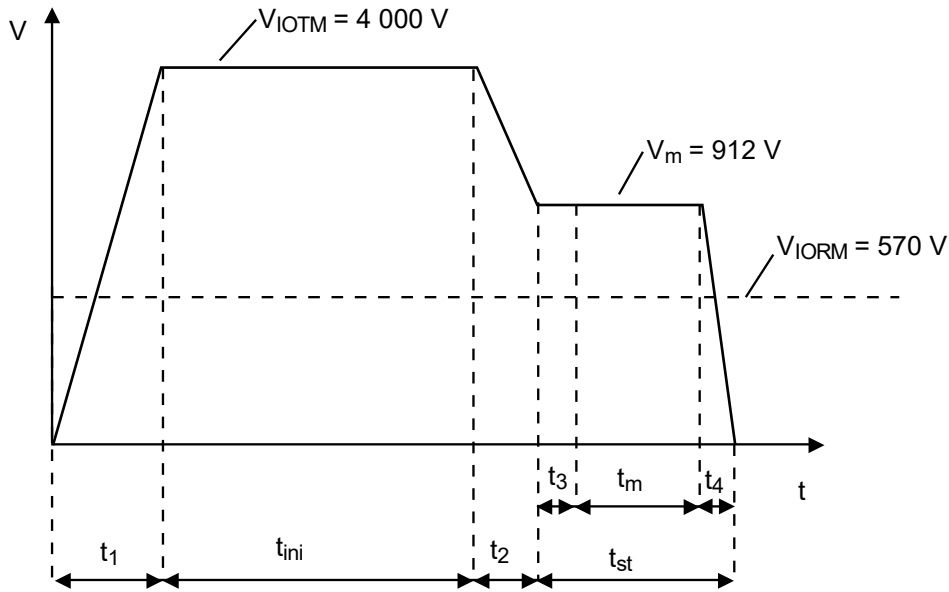
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength			
maximum operating isolation voltage	$V_{IORM}$	570	$V_{peak}$
Test voltage (partial discharge test, procedure a for type test and random test)	$V_m$	912	$V_{peak}$
$V_m = 1.6 \times V_{IORM}, q_{pd} < 5 \text{ pC}$			
Test voltage (partial discharge test, procedure b for all devices)	$V_m$	1 069	$V_{peak}$
$V_m = 1.875 \times V_{IORM}, q_{pd} < 5 \text{ pC}$			
Highest permissible overvoltage	$V_{IOTM}$	4 000	$V_{peak}$
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	$T_{stg}$	-55 to +150	°C
Operating temperature range	$T_A$	-55 to +100	°C
Isolation resistance, minimum value			
$V_{I-O} = 500 \text{ V dc}, T_A = 25 \text{ °C}$	$R_{I-O \text{ MIN.}}$	$10^{12}$	$\Omega$
$V_{I-O} = 500 \text{ V dc}, T_A = \text{maximum temperature of rating, at least } 100 \text{ °C}$	$R_{I-O \text{ MIN.}}$	$10^{11}$	$\Omega$
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve)			
Maximum ambient temperature	$T_s$	150	°C
Maximum input current	$I_{SI}$	300	mA
Maximum output power dissipation	$P_{SO}$	500	mW
Isolation resistance, minimum value at $V_{I-O} = 500 \text{ V dc}, T_A = T_s$	$R_{I-O \text{ MIN.}}$	$10^9$	$\Omega$

Dependence of maximum safety ratings with ambient temperature

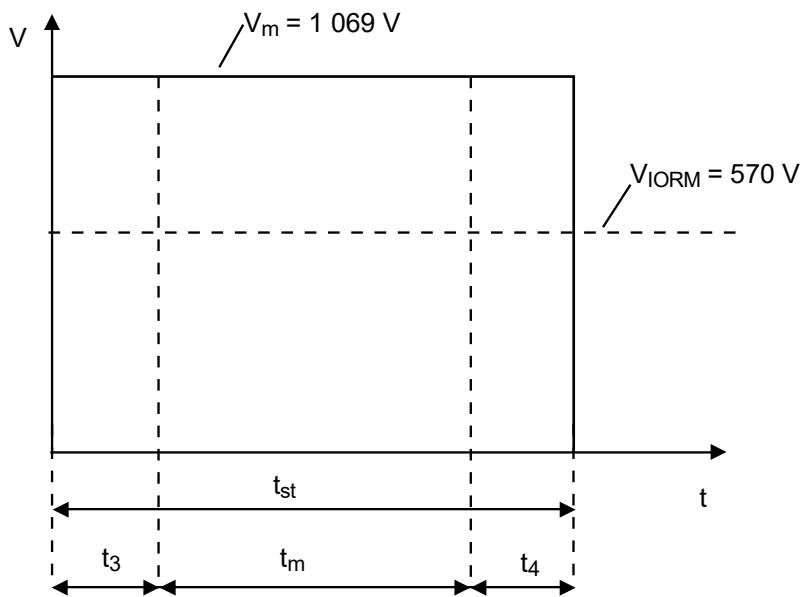


Method a) Destructive Test, Type and Sample Test



$t_1, t_2 = 1\text{ to }10\text{ sec}$   
 $t_3, t_4 = 1\text{ sec}$   
 $t_m = 10\text{ sec}$   
 $t_{st} = 12\text{ sec}$   
 $t_{ini} = 60\text{ sec}$

Method b) Non-destructive Test, 100% Production Test



$t_3, t_4 = 0.1\text{ sec}$   
 $t_m = 1.0\text{ sec}$   
 $t_{st} = 1.2\text{ sec}$

<b>Caution</b>	GaAs Products	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"><li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.<ol style="list-style-type: none"><li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li><li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li></ol></li><li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li><li>• Do not lick the product or in any way allow it to enter the mouth.</li></ul>
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